TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $L^2-\pi$ -MOSIII)

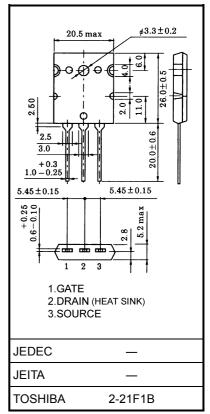
# 2SK1382

Relay Drive, Motor Drive and DC–DC Converter Applications

- 4 V gate drive
- Low drain-source ON resistance  $: R_{DS} (ON) = 15 m\Omega (typ.)$
- High forward transfer admittance  $|Y_{fs}| = 47 \text{ S} (\text{typ.})$
- Low leakage current  $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 100 \ V)$
- Enhancement-mode :  $V_{th} = 0.8 \sim 2.0 V (V_{DS} = 10 V, I_D = 1 mA)$

#### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	100	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		V <sub>DGR</sub>	100	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	60	А	
	Pulse (Note 1)	I <sub>DP</sub>	240	4	
Drain power dissipation (Tc = 25°C)		PD	200	W	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	



**Thermal Characteristics** 

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch−c)</sub>	0.625	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch−a)</sub>	35.7	°C / W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

This transistor is an electrostatic sensitive device. Please handle with caution. Weight: 9.75 g (typ.)

Unit: mm

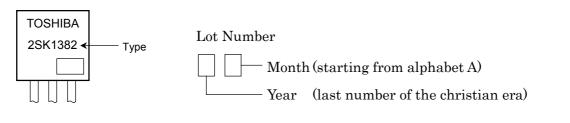
Electrical Characteristics (Ta = 25°C)

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±100	nA
Drain cut-off cu	rrent	IDSS	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	100	_	_	V
Gate threshold	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8		2.0	V
Drain-source ON resistance		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 30 A		20	29	mΩ
			V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		15	20	
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 30 A	30	47	_	S
Input capacitance	ce	C <sub>iss</sub>		_	7000	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	400	_	pF
Output capacitance		C <sub>oss</sub>		_	2700	_	
Switching time	Rise time	tr	$v_{GS} \stackrel{10V}{}_{0V} \int I_{D} = 30A$ $V_{OUT}  V_{OUT}$ $R_{L} = 1.6\Omega$	_	16	_	
	Turn-on time	t <sub>on</sub>		_	55	_	- ns
	Fall time	t <sub>f</sub>		_	80	_	
	Turn-off time	t <sub>off</sub>	$V_{DD}$ $\doteqdot$ 50V Duty $\leq$ 1%, t <sub>w</sub> =10 $\mu$ s	_	280	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	176	_	
Gate-source charge		Q <sub>gs</sub>	V <sub>DD</sub> ≈ 80 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 60 A		132	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>	]	_	44	_	

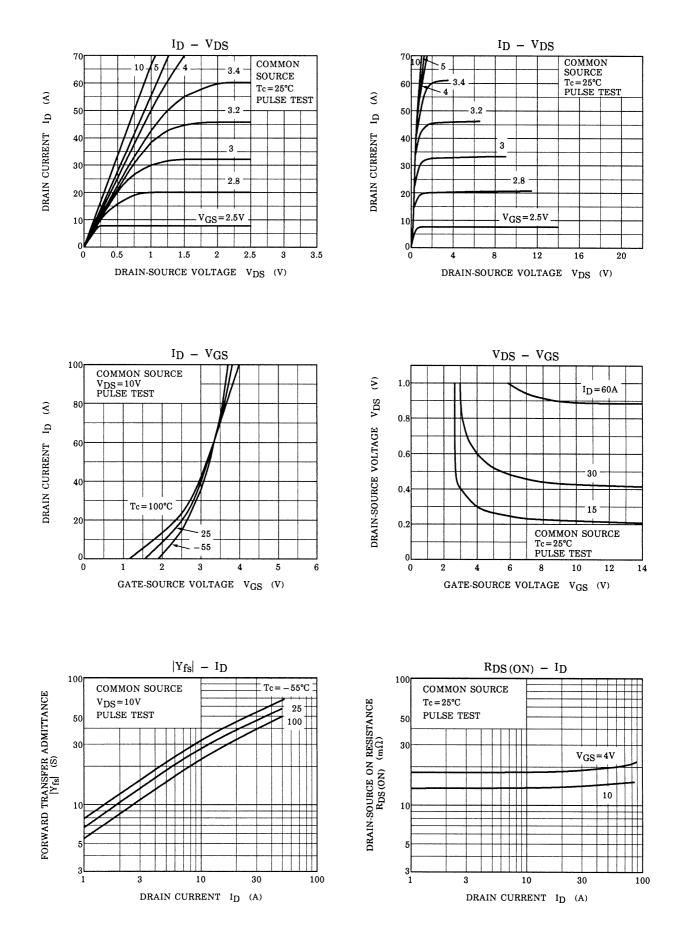
### Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	—	_	_	60	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	—	_	_	240	A
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 60 A, V <sub>GS</sub> = 0 V	_	_	-1.6	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 60 A, V <sub>GS</sub> = 0 V	_	300	—	ns
Reverse recovered charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 50 Å / µs	_	0.75	—	μC

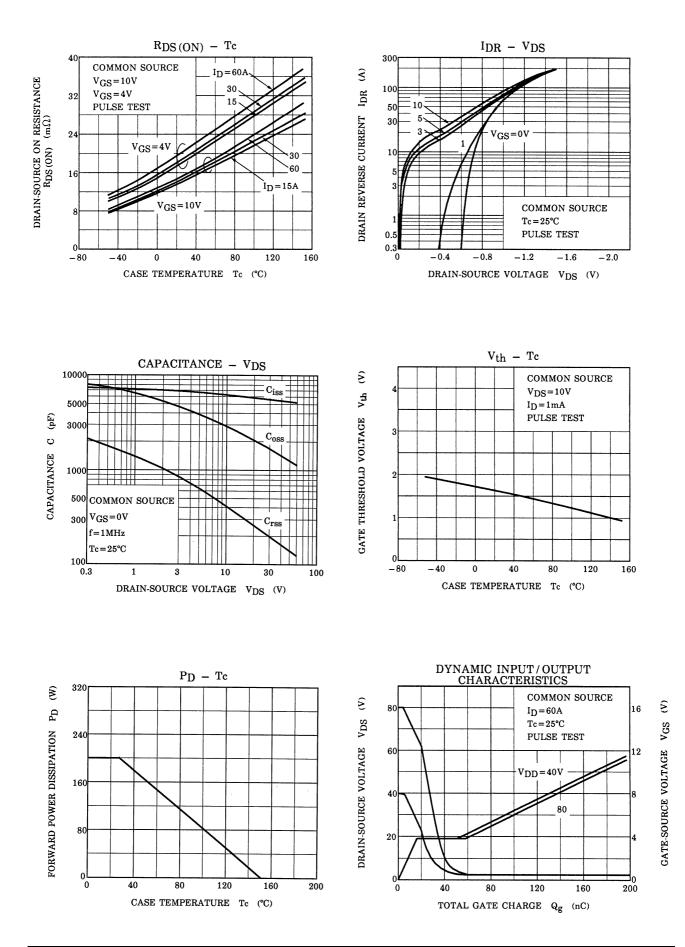
#### Marking

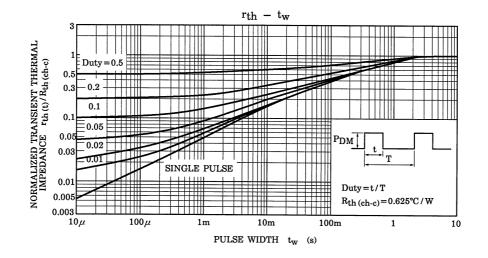


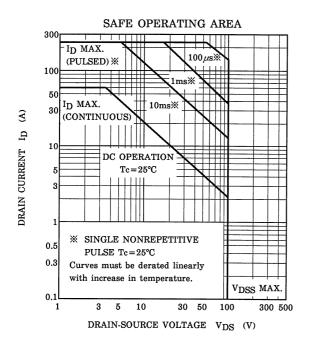
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